

Advanced Product / Process Change Notice

No.: Z200-APCN-DM202404-02-P Date: April 16, 2024 Change Title: 2Gb (128Mb x16 and 256Mb x8) DDR3/DDR3L technology migration from 25nm to 20nm. Change Classification: ☑ Major ☐ Minor with customer notification ☐ Minor without customer notification Change item: □ DataSheet ☑ Design □ Raw Material □ Wafer FAB □ Assembly □ Testing □ Packing □ Manufacture site □ Others Affected Product(s): Please refer to Table 1 in details. Description of Change(s): Technology migration (25nm to 20nm) for 2Gb DDR3/DDR3L. Reason for Change(s): According to Winbond product roadmap, a new 2Gb DDR3/DDR3L using the 20nm process was launched. Impact of Change(s): (positive & negative) Form: No Change Fit: No Change (Please refer to attachment I) Function: No Concern (Compatible between 25nm and 20nm, refer to attachment II) Reliability: On-going (The reliability report will be ready in Jun' 2024) Hazardous Substances: No Concern (Please refer to attachment III) Qualification Plan/ Results: The new sample has passed ESD, HBM 2KV, Latch-up 200mA and full qualification is in progress. The result is expected out on June 2024. Implementation Plan: The follow-up disposition of 25nm 128Mb x16 DDR3/DDR3L and 256Mb x8 DDR3/DDR3L: 1) The date of last-buy orders for the 25nm 128Mb x16 and 256Mb x8 DDR3/DDR3L: October 21, 2024. 2) The last shipment date of the 25nm 128Mb x16 and 256Mb x8 DDR3/DDR3L: January 20, 2025. ■ Date Code: onward □ Lot No: onward ☑ Proposed first ship date: July 19, 2024 Originator: Approval: (QA Approval: Yhuang (QRA Director) (QA) Dept. Manager) Name: Betty Huang TEL:886-3-5678168 (ext.76549) FAX: 886-3-5796124 Address: No. 8, Keya 1st Rd., Daya Dist., Central Taiwan Science Park, Taichung **Contact for Questions** City 42881, Taiwan & Concerns E-mail: Hyhuang8@winbond.com

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Table No.: 1110-0001-08-A



Customer Comments:

Note: Please sign this notice, and return to Winbond contact within **30** days. If no response is received within **30** days, this Change Request will be assumed to meet your approval.

Major change: ☐ Approval	■ Disapproval	□ Conditional Approval :					
Minor change with customer notification: □ Recognition							
Minor change without customer notification: □ Approval □ Disapproval							
□ Conditional Approval :		<u></u>					
Comment:							
Date:							
Dept. name:							
Person in charge:		<u></u>					



Table 1. The affected part no is listed below.

W632GG6NB-09	W632GG6NB-15	W632GU6NB11J	W632GG8NB09I	W632GU8NB09I
W632GG6NB09I	W632GG6NB15I	W632GU6NB-12	W632GG8NB-11	W632GU8NB-11
W632GG6NB09J	W632GG6NB15J	W632GU6NB12I	W632GG8NB11I	W632GU8NB11I
W632GG6NB-11	W632GU6NB-09	W632GU6NB12J	W632GG8NB-12	W632GU8NB11J
W632GG6NB11I	W632GU6NB09I	W632GU6NB-15	W632GG8NB12I	W632GU8NB-12
W632GG6NB11J	W632GU6NB09J	W632GU6NB15I	W632GG8NB-15	W632GU8NB12I
W632GG6NB-12	W632GU6NB-11	W632GU6NB15J	W632GG8NB15I	W632GU8NB-15
W632GG6NB12I	W632GU6NB11I	W632GG8NB-09	W632GU8NB-09	W632GU8NB15I
W632GG6NB12.I				

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